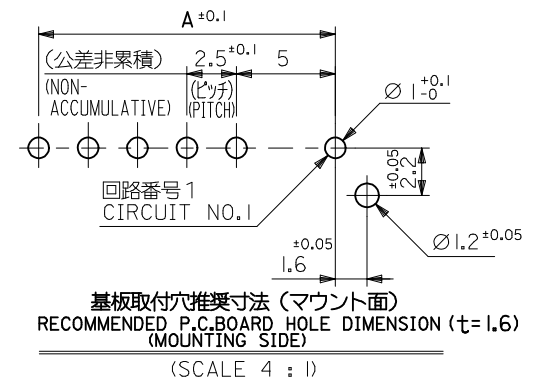
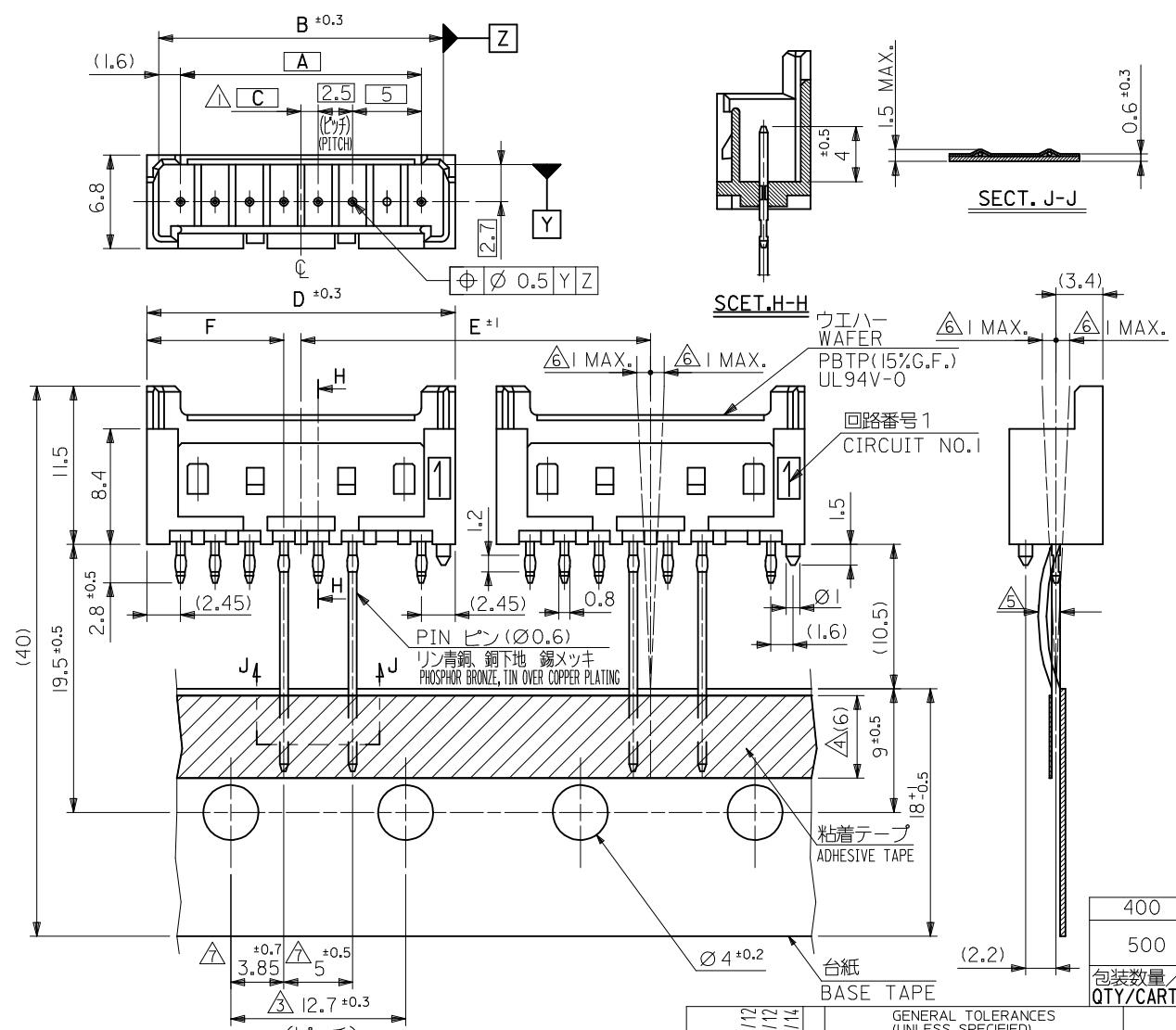


10 9 8 7 6 5 4 3 2 1



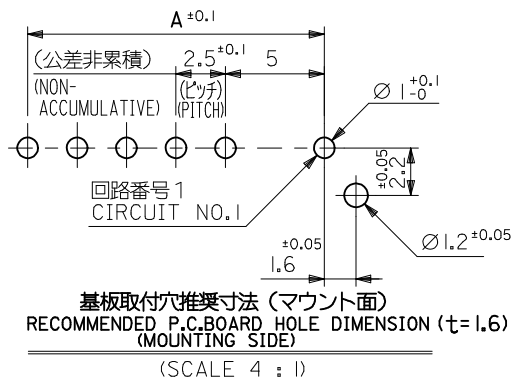
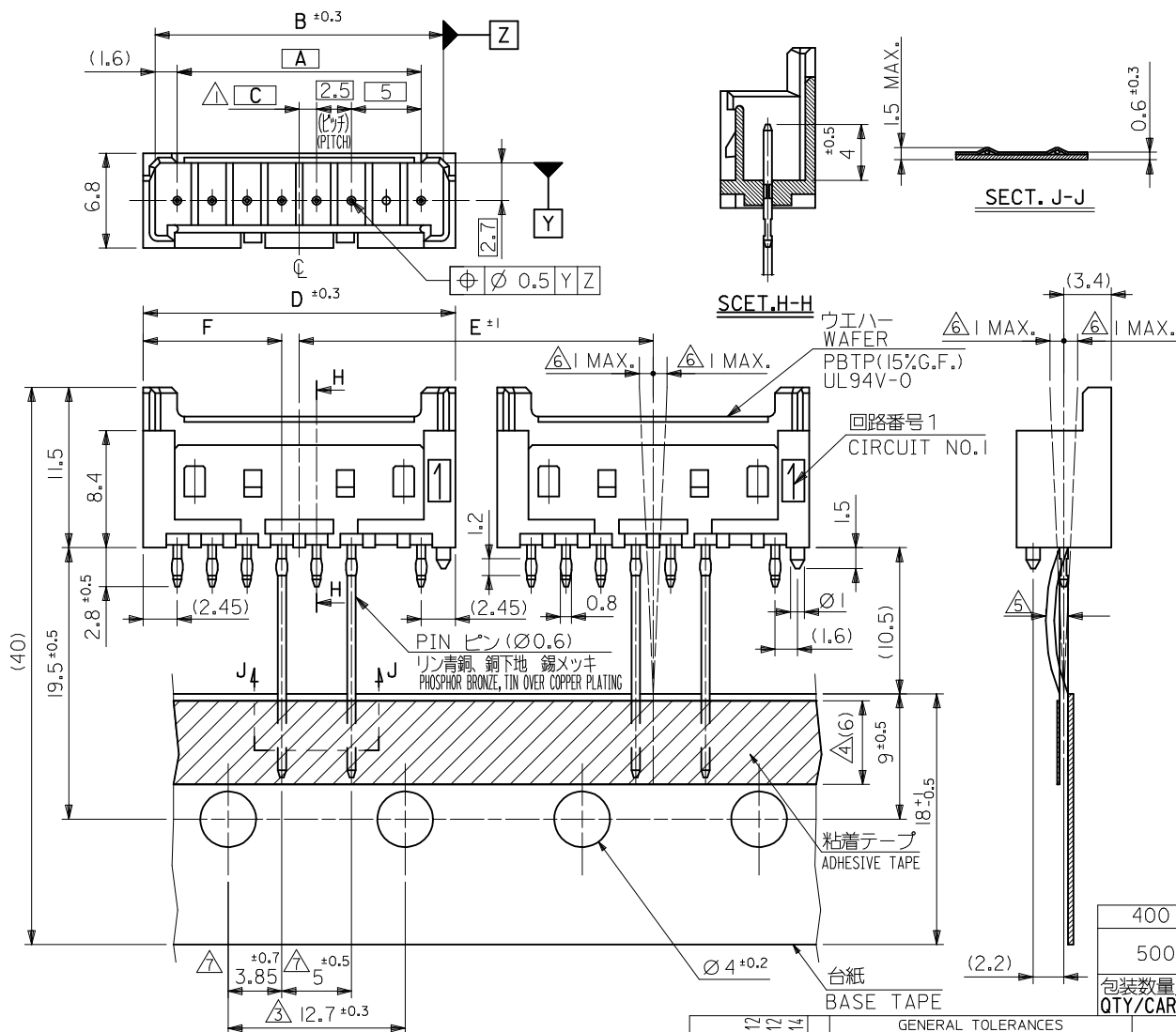
- 注記 NOTES**
- △ ウエハーの  $\phi$  から隣接するピン  $\phi$  までの位置を示す。  
SHOW POSITION FROM  $\phi$  OF WAFER TO  $\phi$  OF ADJACENT PIN.
  - 2. 嵌合相手: 51102, 51103 シリーズ  
MATES WITH: 51102, 51103 SERIES.
  - △ 累積ピッチの許容差は、20ピッチで ±1.0mm とする。  
ACCUMULATED TOLERANCE IS TO BE ±1.0mm PER 20 PITCH.
  - △ 粘着テープは台紙からはみ出さないこと。  
THE ADHESIVE TAPE SHOULD NOT BE PROTRUDED FROM THE BASE TAPE.
  - △ リード線の曲がりの許容差は 1mm MAX. とする。  
CAMBER OF THE LEADS: 1mm MAX.
  - △ 測定位置は、コネクタの先端とする。  
INCLINED POSITION FROM THE CENTER-LINE, SHOULD BE 1mm MAX. MEASURING SHOULD BE DONE, USING THE TOP OF BASE TAPE AS DATUM.
  - △ 測定位置は、台紙の上端とし、リード線の中心線との間隔とする。  
DIM. 3.85 AND DIM. 5 SHOULD BE MEASURED ON THE TOP OF BASE TAPE. DIMENSIONS ARE A SPACING BETWEEN THE CENTER-LINES.

400	7.45	25.4	19.9	2.5	18.2	15	53389-0690	6
500	4.95	25.4	14.9	3.5	13.2	10	53389-0490	4
	4.95	25.4	12.4	3.25	10.7	7.5	53389-0390	3
包装数量/箱 QTY/CARTON	F	E	D	C	B	A	MATERIAL NO.	極数 NO. OF CKTS.

REVISED EC NO: J2017-0224 DRW: M. SHIKAWA 2016/10/12 CHK: K. TAKAHASHI 2016/10/12 APP: M. SASAO 2016/10/14	GENERAL TOLERANCES (UNLESS SPECIFIED)			DIMENSION STYLE MM ONLY		SCALE 3:1	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION
	0.25 UNDER		±	DRAWN BY K. TOJO	DATE 1992/12/22	TITLE 5/2.5 WIRE TO BOARD CONN. WAFER ASSY -LEAD FREE-		
	0.25 OVER	0.5 UNDER	±	CHECKED BY T. YAMAGUCHI	DATE 2000/08/22	DOCUMENT NO. SD-53389-**90		
	0.5 OVER	1.0 UNDER	±	APPROVED BY M. FUKUSHIMA	DATE 2000/08/22			
	0 OVER	10 UNDER	±0.2	MATERIAL NO. SEE CHART		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX ELECTRONIC TECHNOLOGIES, LLC AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION		
10 OVER	30 UNDER	±0.25	ANGULAR ±3 °					
REV	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS			SIZE A3				

9 8 7 6 5 4 3 2 1

10 9 8 7 6 5 4 3 2 1



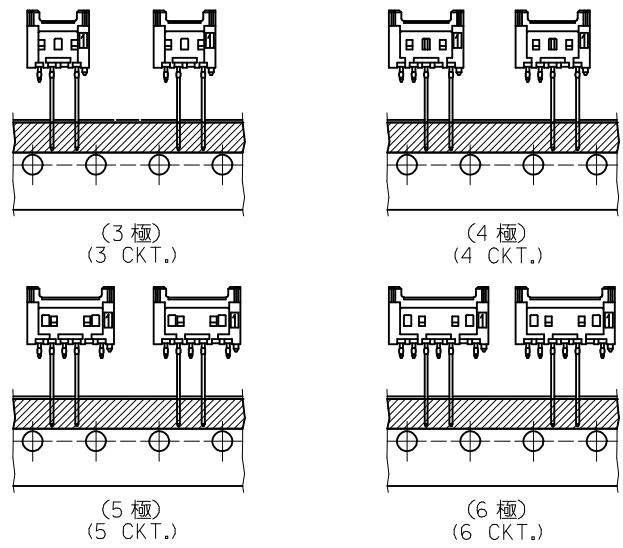
- 注記 NOTES**
- △ ウエハーの  $\phi$  から隣接するピンの  $\phi$  までの位置を示す。  
SHOW POSITION FROM  $\phi$  OF WAFER TO  $\phi$  OF ADJACENT PIN.
  - 2. 嵌合相手: 51102, 51103 シリーズ  
MATES WITH: 51102, 51103 SERIES.
  - △ 累積ピッチの許容差は、20ピッチで  $\pm 1.0\text{mm}$  とする。  
ACCUMULATED TOLERANCE IS TO BE  $\pm 1.0\text{mm}$  PER 20 PITCH.
  - △ 粘着テープは台紙からはみ出さないこと。  
THE ADHESIVE TAPE SHOULD NOT BE PROTRUDED FROM THE BASE TAPE.
  - △ リード線の曲がりの許容差は  $1\text{mm}$  MAX. とする。  
CAMBER OF THE LEADS:  $1\text{mm}$  MAX.
  - △ 測定位置は、コネクタの先端とする。  
INCLINED POSITION FROM THE CENTER-LINE, SHOULD BE  $1\text{mm}$  MAX. MEASURING SHOULD BE DONE, USING THE TOP OF BASE TAPE AS DATUM.
  - △ 測定位置は、台紙の上端とし、リード線の中心線との間隔とする。  
DIM. 3.85 AND DIM. 5 SHOULD BE MEASURED ON THE TOP OF BASE TAPE. DIMENSIONS ARE A SPACING BETWEEN THE CENTER-LINES.

400	7.45	25.4	19.9	2.5	18.2	15	53389-0690	6
500	4.95	25.4	14.9	3.5	13.2	10	53389-0490	4
	4.95	25.4	12.4	3.25	10.7	7.5	53389-0390	3

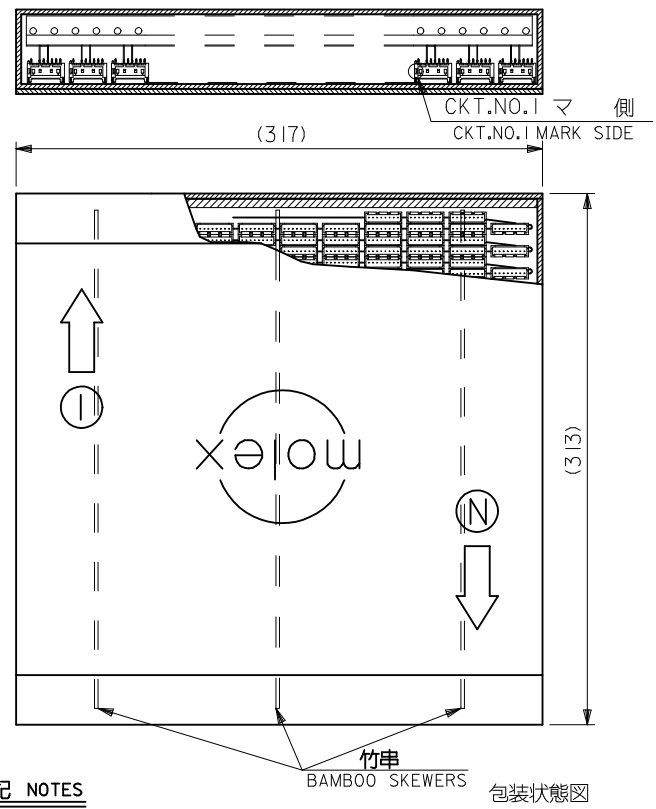
REVISED EC NO: J2017-0224 DRAWN: M. SHIKAWA 2016/10/12 CHKD: K. TAKAHASHI 2016/10/12 APPR: M. SASAO 2016/10/14	GENERAL TOLERANCES (UNLESS SPECIFIED)			DIMENSION STYLE <b>MM ONLY</b>		SCALE 3:1	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION
	0.25 UNDER		±	DRAWN BY K. TOJO	DATE 1992/12/22	TITLE 5/2.5 WIRE TO BOARD CONN. WAFER ASSY -LEAD FREE-		
	0.25 OVER	0.5 UNDER	±	CHECKED BY T. YAMAGUCHI	DATE 2000/08/22	<b>molex</b>		
	0.5 OVER	1.0 UNDER	±	APPROVED BY M. FUKUSHIMA	DATE 2000/08/22			
0 OVER	10 UNDER	±0.2	MATERIAL NO.		DOCUMENT NO. SD-53389-**90	SHEET NO. 1 OF 2		
10 OVER	30 UNDER	±0.25	SEE CHART		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX ELECTRONIC TECHNOLOGIES, LLC AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION			
30 OVER		±0.3	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SIZE A3			

9 8 7 6 5 4 3 2 1

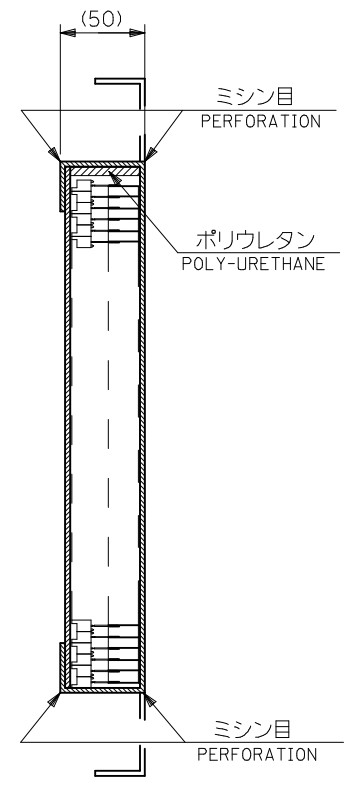
10 9 8 7 6 5 4 3 2 1



極数別テーピング状態図  
CKT.TAPING FORM

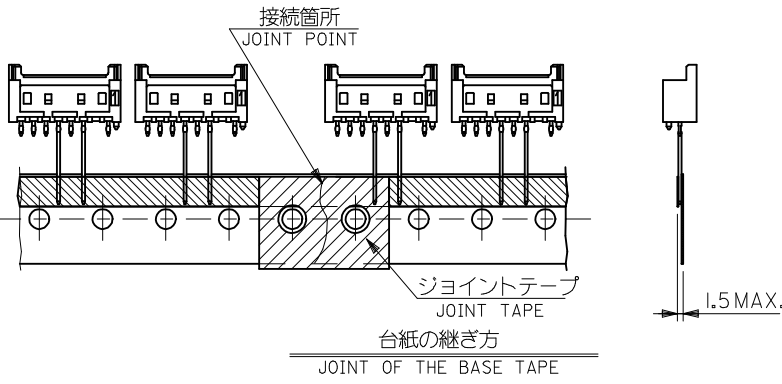


包装状態図  
PACKAGING FORM



注記 NOTES

1. 包装形態はつづら折りで箱詰め。  
RADIAL TAPE IS FOLDED AND PILED IN THE CARTON.
2. テーピングの両端には、5個以上の送り穴を設けること。  
BOTH ENDS OF TAPING, MORE THAN 5 FEEDING HOLES SHOULD BE PROVIDED.
3. コネクタの欠落数は、1個とする。(折り目ごとの1個抜きも含む)  
ALLOWABLE NUMBERS OF CONSECUTIVE MISSING CONNECTORS IS ONE.
4. 台紙の継ぎ目のずれは、いかなる方向からも±0.3以内とする。  
MISMATCHED JOINT OF THE BASE TAPE SHOULD BE KEPT WITHIN ±0.3mm IN EVERY DIRECTIONS.
5. 日本工業規格 JIS C08050 電子部品のテーピング \* を適用。  
ITEMS UNLESS OTHERWISE SPECIFIED, JIS C 0805 (TAPING OF ELECTRONIC COMPONENTS) SHOULD BE APPLIED.

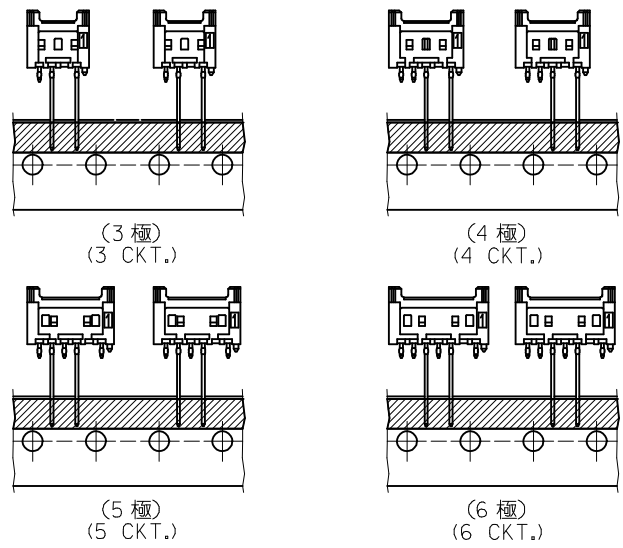


台紙の継ぎ方  
JOINT OF THE BASE TAPE

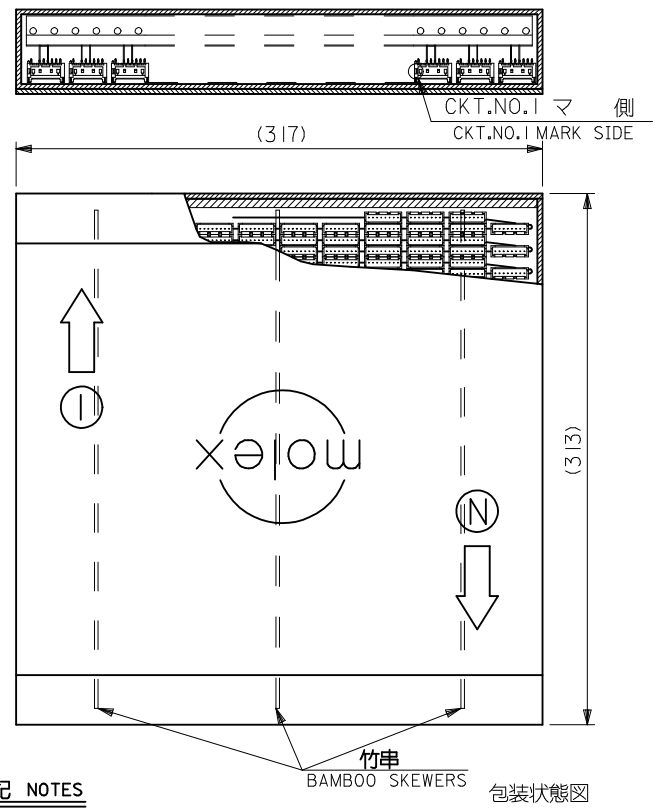
REVISED EC NO: J2017-0224 DRAWN: M. SHIKAWA 2016/10/12 CHKD: K. TAKAHASHI 2016/10/12 APPR: M. SASAO 2016/10/14	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE 3:1	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION
	0.25 UNDER	+	DRAWN BY K. TOJO	DATE 1992/12/22	TITLE 5/2.5 WIRE TO BOARD CONN. WAFER ASSY -LEAD FREE-		
	0.25 OVER	±	CHECKED BY T. YAMAGUCHI	DATE 2000/08/22			
	0.5 OVER	±	APPROVED BY M. FUKUSHIMA	DATE 2000/08/22	<b>molex</b> DOCUMENT NO. SD-53389-**-90 SHEET NO. 2 OF 2		
	0 OVER	±0.2	MATERIAL NO.				
10 OVER	±0.25	SEE CHART					
30 OVER	±0.3	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX ELECTRONIC TECHNOLOGIES, LLC AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION			

9 8 7 6 5 4 3 2 1

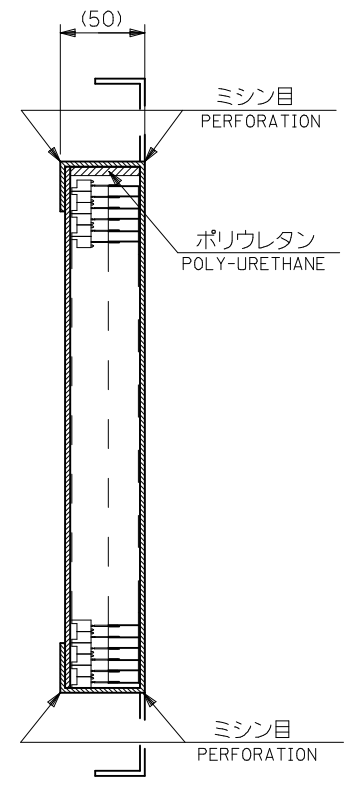
10 9 8 7 6 5 4 3 2 1



極数別テーピング状態図  
CKT.TAPING FORM

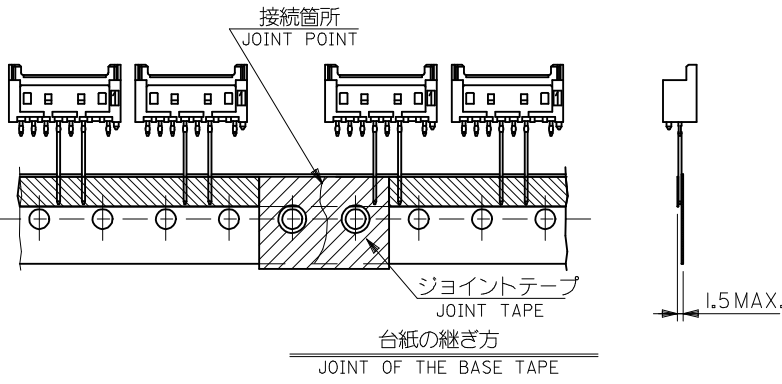


包装状態図  
PACKAGING FORM



注 記 NOTES

1. 包装形態はつづら折りで箱詰め。  
RADIAL TAPE IS FOLDED AND PILED IN THE CARTON.
2. テーピングの両端には、5個以上の送り穴を設けること。  
BOTH ENDS OF TAPING, MORE THAN 5 FEEDING HOLES SHOULD BE PROVIDED.
3. コネクタの欠落数は、1個とする。(折り目ごとの1個抜きも含む)  
ALLOWABLE NUMBERS OF CONSECUTIVE MISSING CONNECTORS IS ONE.
4. 台紙の継ぎ目のずれは、いかなる方向からも±0.3以内とする。  
MISMATCHED JOINT OF THE BASE TAPE SHOULD BE KEPT WITHIN ±0.3mm IN EVERY DIRECTIONS.
5. 日本工業規格 JIS C08050 電子部品のテーピング \*を適用。  
ITEMS UNLESS OTHERWISE SPECIFIED, JIS C 0805 (TAPING OF ELECTRONIC COMPONENTS) SHOULD BE APPLIED.



REVISED EC NO: J2017-0224 DRAWN: M. SHIKAWA 2016/10/12 CHKD: K. TAKAHASHI 2016/10/12 APPR: M. SASAO 2016/10/14	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE		SCALE	DESIGN UNITS	THIRD ANGLE PROJECTION	
			MM ONLY		3:1	METRIC		
	0.25 UNDER	+	DRAWN BY	DATE	TITLE			
	0.25 OVER	±	K. TOJO	1992/12/22	5/2.5 WIRE TO BOARD CONN. WAFER ASSY -LEAD FREE-			
	0.5 OVER	±	CHECKED BY	DATE	molex			
0 OVER	±0.2	T. YAMAGUCHI	2000/08/22					
10 OVER	±0.25	APPROVED BY	DATE	DOCUMENT NO.		SHEET NO.		
30 OVER	±0.3	M. FUKUSHIMA	2000/08/22	SD-53389-**-90		2 OF 2		
ANGULAR ±3 °		MATERIAL NO.		SEE CHART				
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SIZE A3		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX ELECTRONIC TECHNOLOGIES, LLC AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION				

9 8 7 6 5 4 3 2 1